

In the Claims:

Please amend claims 1, 8, 13, and 20. Please add new claims 21-22. The claims are as follows:

1. (Currently amended) A method of printing a wafer, comprising printing a design only within a peripheral portion of the wafer such that no portion of the printed design is within the active portion of the wafer, wherein the peripheral portion of the wafer is between an outer boundary of the active portion of the wafer and an outer boundary of the wafer.
2. (Original) The method of claim 1, further comprising passing light through an exposure apparatus having a reticle and a reticle blind, wherein the reticle includes a pattern, wherein a first portion of the light is blocked by the reticle blind, wherein a remaining portion of the light passes through a transparent portion of the reticle and is focused onto the wafer by a lens of the apparatus, wherein the remaining portion of the light prints the design as an image of a portion of the pattern, and wherein the printed design is a function of where the reticle blind is positioned relative to the pattern.
3. (Original) The method of claim 2, wherein the pattern includes a plurality of pattern elements such that adjacent pattern elements are separated by a spacing.
4. (Original) The method of claim 3, wherein the spacing is about equal to a design tolerance,

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wherein the design tolerance is a sum of a first design tolerance and a second design tolerance, wherein the first design tolerance is based on how accurately the reticle blind can be positioned within the exposure apparatus, and wherein the second design tolerance is based on how sharply an edge of the reticle blind can be focused on the wafer by a lens of the exposure apparatus.

5. (Original) The method of claim 4, wherein the printed design measures, to within the design tolerance, where the reticle blind is positioned relative to the pattern.

6. (Original) The method of claim 2, wherein the remaining portion of the light prints a device field within the active portion of the wafer, and wherein the device field and the design are each adjacent to a same portion of the outer boundary of the active portion of the wafer.

7. (Original) The method of claim 6, wherein the wafer is a semiconductor wafer, and wherein the device field includes at least one integrated circuit chip.

8. (Currently amended) An exposure apparatus for printing a wafer, comprising:

a lens;

a reticle that includes a pattern; and

a reticle blind, wherein the reticle blind is adapted to block a first portion of light that is passed through the exposure apparatus, wherein a transparent portion of the reticle is adapted to transmit a remaining portion of the light, wherein the lens is adapted to focus the remaining portion of the light onto the wafer such that an image of a portion of the pattern is printed as a

design only within a peripheral portion of the wafer such that no portion of the printed design is within the active portion of the wafer, wherein the peripheral portion of the wafer is between an outer boundary of the active portion of the wafer and an outer boundary of the wafer, and wherein the printed design is a function of where the reticle blind is positioned relative to the pattern.

9. (Original) The apparatus of claim 8, wherein the pattern includes a plurality of pattern elements such that adjacent pattern elements are separated by a spacing.

10. (Original) The apparatus of claim 9, wherein the spacing is about equal to a design tolerance, wherein the design tolerance is a sum of a first design tolerance and a second design tolerance, wherein the first design tolerance is based on how accurately the reticle blind can be positioned within the exposure apparatus, and wherein the second design tolerance is based on how sharply an edge of the reticle blind can be focused onto the wafer by the lens of the exposure apparatus.

11. (Original) The apparatus of claim 10, wherein the printed design measures, to within the design tolerance, where the reticle blind is positioned relative to the pattern.

12. (Original) The apparatus of claim 8, wherein the remaining portion of the light prints a device field within the active portion of the wafer, and wherein the device field and the design are each adjacent to a same portion of the outer boundary of the active portion of the wafer.

13. (Currently amended) A printed wafer, comprising:

a design printed only within a peripheral portion of the wafer such that no portion of the printed design is within the active portion of the wafer, wherein the peripheral portion of the wafer is between an outer boundary of the active portion of the wafer and an outer boundary of the wafer.

14. (Original) The printed wafer of claim 13, wherein the design is a copy of a portion of a pattern that exists on a reticle of an exposure apparatus.

15. (Original) The printed wafer of claim 14, wherein the portion of the pattern is a function of where a reticle blind of the exposure apparatus is located relative to the pattern.

16. (Original) The printed wafer of claim 14, wherein the pattern includes a plurality of pattern elements such that adjacent pattern elements are separated by a spacing.

17. (Original) The printed wafer of claim 16, wherein the spacing is about equal to a design tolerance, wherein the design tolerance is a sum of a first design tolerance and a second design tolerance, wherein the first design tolerance is based on how accurately a reticle blind of the exposure apparatus can be positioned within the exposure apparatus, and wherein the second design tolerance is based on how sharply an edge of the reticle blind can be focused on the wafer by a lens of the exposure apparatus.

18. (Original) The printed wafer of claim 13, wherein an active portion of the wafer includes a device field, and wherein the device field and the design are each adjacent to a same portion of the outer boundary of the active portion of the wafer.

19. (Original) The printed wafer of claim 18, wherein the wafer is a semiconductor wafer, and wherein the device field includes at least one integrated circuit chip.

20. (Currently amended) ~~The printed wafer of claim 13~~ A printed wafer, comprising:
a design printed only within a peripheral portion of the wafer, wherein the peripheral
portion of the wafer is between an outer boundary of the active portion of the wafer and an outer
boundary of the wafer, and wherein the design is visible to a naked eye.

21. (New) The printed wafer of claim 20, wherein the design is visible to the naked eye unaided.

22. (New) The printed wafer of claim 20, wherein the design is visible to the naked eye with use of one or more vision aids.